

# ZXM62P02E6TA Datasheet



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DiGi Electronics Part Number ZXM62P02E6TA-DG

Manufacturer Diodes Incorporated

Manufacturer Product Number ZXM62P02E6TA

Description MOSFET P-CH 20V 2.3A SOT23-6

Detailed Description P-Channel 20 V 2.3A (Ta) 1.1W (Ta) Surface Mount

SOT-23-6



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## **Purchase and inquiry**

Manufacturer Product Number:	Manufacturer:
ZXM62P02E6TA	Diodes Incorporated
Series:	Product Status:
	Active
FET Type:	Technology:
P-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
20 V	2.3A (Ta)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
2.7V, 4.5V	200m0hm @ 1.6A, 4.5V
Vgs(th) (Max) @ ld:	Gate Charge (Qg) (Max) @ Vgs:
700mV @ 250µA (Min)	5.8 nC @ 4.5 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±12V	320 pF @ 15 V
FET Feature:	Power Dissipation (Max):
	1.1W (Ta)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
SOT-23-6	SOT-23-6
Base Product Number:	
7VM62D02	

## **Environmental & Export classification**

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	





#### 20V P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C
-20V	200mΩ @ V <sub>GS</sub> = -4.5V	-2.3A

### **Description**

This new generation of high density MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

## **Applications**

- DC DC Converters
- **Power Management Functions**
- **Disconnect Switches**
- Motor Control

## **Features and Benefits**

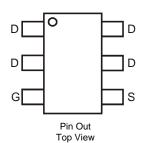
- Low On-resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

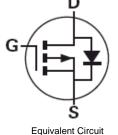
#### **Mechanical Data**

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.018 grams (Approximate)









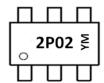
## Ordering Information (Note 4)

Part Number	Reel Size (inch)	Tape Width (mm)	Quantity Per Reel
ZXM62P02E6TA	7	8	3,000
ZXM62P02E6TC	13	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and -1000ppm antimony compounds.
   4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



2P02 = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: C = 2015) M or  $\overline{M}$  = Month (ex: 9 = September)

#### Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026
Code	С	D	Е	F	G	Н	ı	J	K	L	М	N
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code			_									Ъ



## **Absolute Maximum Ratings**

(	Characteristic		Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	-20	V
Gate-Source Voltage			V <sub>GSS</sub>	±12	V
Continuous Drain Current	\/ 4.5\/	T <sub>A</sub> = +25°C (Note 6)		-2.3	۸
Continuous Drain Current	$V_{GS} = -4.5V$	$T_A = +70^{\circ}C \text{ (Note 6)}$	l <sub>D</sub>	-1.7	A
Pulsed Drain Current		(Note 7)	I <sub>DM</sub>	-13	Α
Continuous Source Current (Body Diode)		(Note 6)	Is	-1.9	Α
Pulsed Source Current (Body Diode)		(Note 7)	I <sub>SM</sub>	-13	А
Power Dissipation at T <sub>A</sub> = +25°C Linear Derating Factor		(Note 5)	P <sub>D</sub>	1.1 8.8	W mW/°C
Power Dissipation at T <sub>A</sub> = +25°C (Note 6)		(Note 6)	P <sub>D</sub>	1.7 13.7	W mW/°C
Operating and Storage Tempe	rature Range	_	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## **Thermal Resistance**

Characteristic	Symbol	Value	Unit	
lunction to Ambient	(Note 5)	9	113	0000
Junction to Ambient	(Note 6)	$R_{ heta JA}$	73	°C/W

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise stated.)

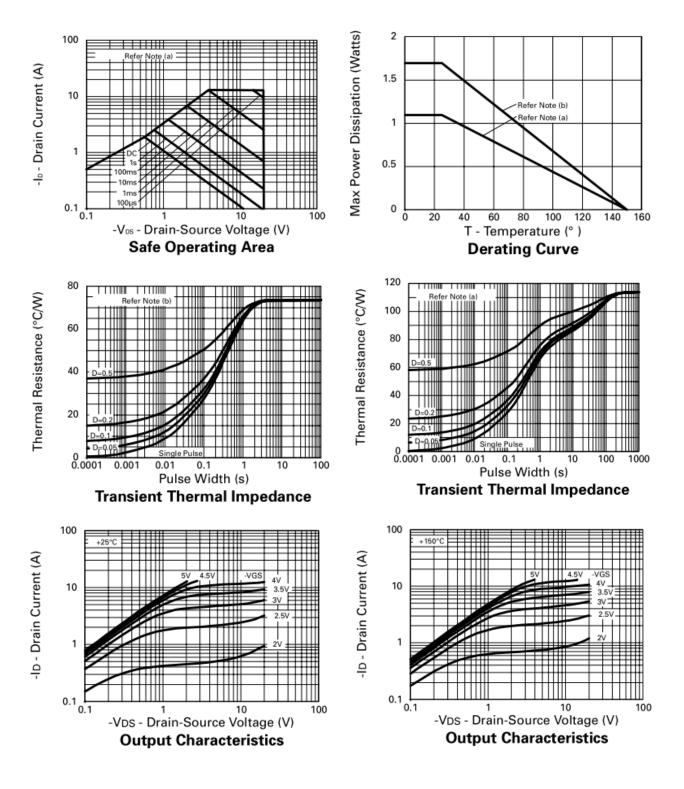
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
STATIC	•					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	V	$I_D = -250 \mu A, V_{GS} = 0 V$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-1	μA	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.7	_	_	V	$I_D = -250 \mu A, V_{DS} = V_{GS}$
Otatia Paria Causas Ca Pariatana (Alata C)				0.2	0	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -1.6A
Static Drain-Source On-Resistance (Note 8)	R <sub>DS(ON)</sub>	_	_	0.375	Ω	V <sub>GS</sub> = -2.7V, I <sub>D</sub> = -0.8A
Forward Transconductance (Note 10)	<b>g</b> fs	1.5	_	_	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -0.8A
DYNAMIC (Note 10)			•			
Input Capacitance	C <sub>iss</sub>		320	_	pF	
Output Capacitance	Coss	_	150	_	pF	$V_{DS} = -15V, V_{GS} = 0V$ -f = 1MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	75	_	pF	1 - 11/11/12
SWITCHING (Notes 9 and 10)						
Total Gate Charge	$Q_g$		_	5.8	nC	V <sub>DS</sub> = -16V, V <sub>GS</sub> = -4.5V
Gate-Source Charge	$Q_{gs}$		_	1.25	nC	I <sub>D</sub> = -1.6A
Gate-Drain Charge	$Q_{gd}$	_	_	2.8	nC	(Refer to test circuit)
Turn-On Delay Time	t <sub>D(ON)</sub>	_	4.1	_	ns	
Turn-On Rise Time	t <sub>R</sub>	_	15.4	_	ns	$V_{DD} = -10V$ , $I_D = -1.6A$ , $R_G = 6\Omega$ ,
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	12.0	_	ns	$R_D = 6.1\Omega$ (Refer to test circuit)
Turn-Off Fall Time	t <sub>F</sub>	_	19.2	_	ns	(Note: to took sinearly
SOURCE-DRAIN DIODE			•			
Diode Forward Voltage (Note 8)	V <sub>SD</sub>			-0.95	V	T <sub>J</sub> = +25°C, I <sub>S</sub> =-1.6A, V <sub>GS</sub> =0V
Reverse recovery time (Note 10)	t <sub>RR</sub>	_	22.5	_	ns	T.j= +25°C, I <sub>F</sub> =-1.6A,
Reverse recovery charge (Note 10)	$Q_{RR}$	_	10.4	_	nC	di/dt= 100A/µs

Notes:

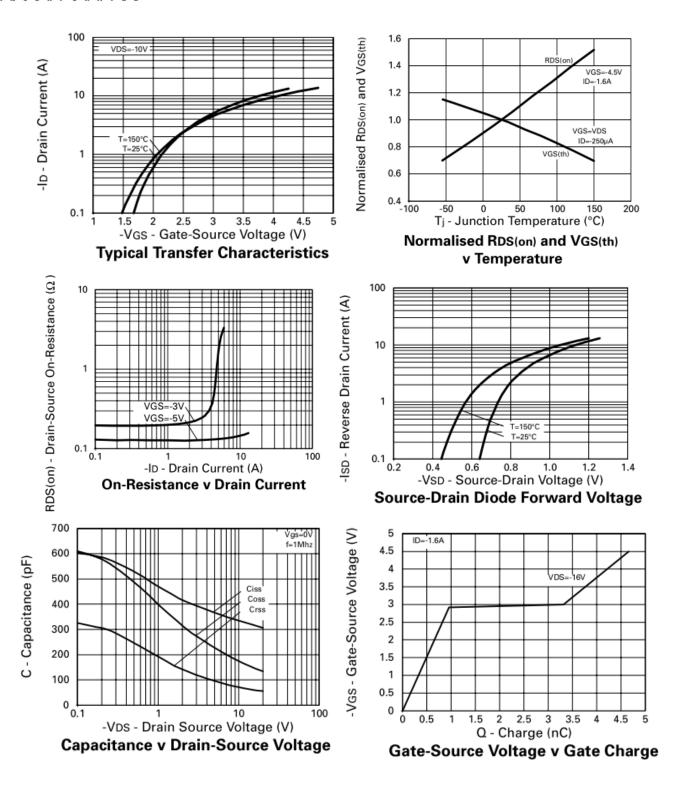
- 5. For a device surface mounted on 25mm x 25mm FR-4 PCB with high coverage of single sided 1oz copper, in still air conditions.
  6. For a device surface mounted on FR-4 PCB measured at t ≤ 5 secs.
  7. Repetitive rating pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.
  8. Measured under pulsed conditions. Width= 300μs; duty cycle ≤ 2%.
  9. Switching characteristics are independent of operating junction temperatures.
  10. For design aid only, not subject to production testing.

- 10. For design aid only, not subject to production testing.



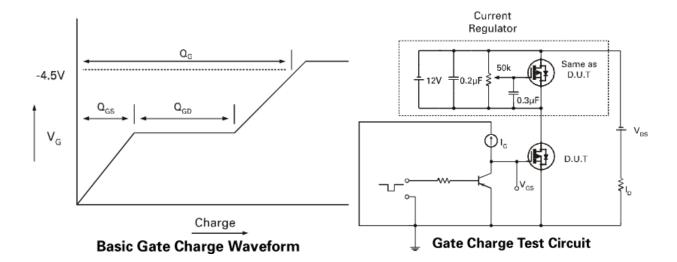


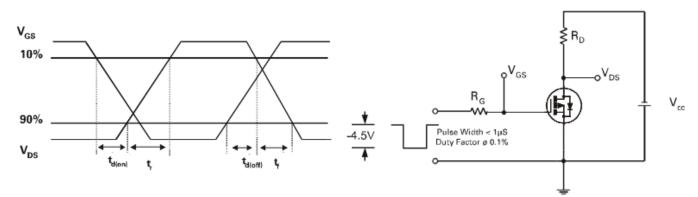






## **Test Circuits**





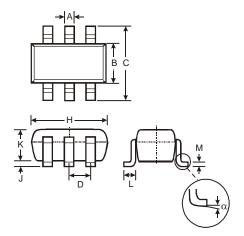
**Switching Time Waveforms** 

**Switching Time Test Circuit** 



## **Package Outline Dimensions**

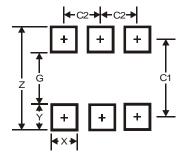
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



	SOT26							
Dim	Min	Max	Тур					
Α	0.35	0.50	0.38					
В	1.50	1.70	1.60					
С	2.70	3.00	2.80					
D	_	_	0.95					
Н	2.90	3.10	3.00					
J	0.013	0.10	0.05					
K	1.00	1.30	1.10					
L	0.35	0.55	0.40					
M	0.10	0.20	0.15					
α	0°	8°	_					
All D	All Dimensions in mm							

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95



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